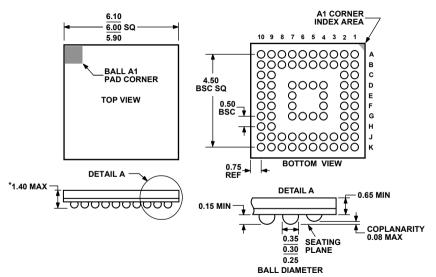


## 76-Ball Chip Scale Package Ball Grid Array [CSP BGA] (BC-76-1)

Dimensions shown in millimeters



\*COMPLIANT TO JEDEC STANDARDS MO-225 WITH THE EXCEPTION TO PACKAGE HEIGHT.

## Analog Devices BC-76-1 REVA < 6.0 ▷ 4.50 6.0 0.40dia —— → 0.50 (Dim. are in MM)

LAST MODIFIED 08/29/2007